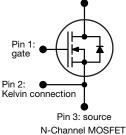
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E Series Power MOSFET





PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650				
R _{DS(on)} typ. (Ω) at 25 °C	$V_{GS} = 10 V$	0.085			
Q _g max. (nC)	129				
Q _{gs} (nC)	20				
Q _{gd} (nC)	44				
Configuration	Single				

Pin 4: drain

FEATURES

- Completely lead (Pb)-free device
- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Q_q)
- Avalanche energy rated (UIS)
- Kelvin connection for reduced gate noise
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Renewable energy
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 8 x 8
Lead (Pb)-free and halogen-free	SiHH28N60E-T1-GE3

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 \degree C$, unless otherwise noted)						
PARAMETER	SYMBOL	LIMIT	UNIT			
Drain-source voltage	V _{DS}	600	v			
Gate-source voltage	V _{GS}	± 30	v			
Continuous drain current (T _J = 150 °C)	V_{GS} at 10 V $T_C = 25 \degree C$ $T_C = 100 \degree C$	- I _D	29			
	$T_{\rm C} = 100 ^{\circ}{\rm C}$		19	А		
Pulsed drain current ^a	I _{DM}	76				
Linear derating factor		1.6	W/°C			
Single pulse avalanche energy ^b	E _{AS}	353	mJ			
Maximum power dissipation	PD	202	W			
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C		
Drain-source voltage slope	T _J = 125 °C	-1) / / -14	70			
Reverse diode dV/dt ^c		dV/dt	13	V/ns		

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

b. V_{DD} = 140 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 5 A

c. $I_{SD} \leq I_D$, dl/dt = 100 A/µs, starting T_J = 25 °C



COMPLIANT

HALOGEN

GREEN

(5-2008)



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THERMAL RESISTANCE RATI	NGS							
PARAMETER	SYMBOL	TYP.		MAX.		UNIT		
Maximum junction-to-ambient	R _{thJA}	38		50				
Maximum junction-to-case (Drain)	R _{thJC}	0.48 0.62					°C/W	
SPECIFICATIONS (T _J = 25 °C, u	nless otherwis	se noted)						
PARAMETER	SYMBOL	TES	T CONDIT	TIONS	MIN.	TYP.	MAX.	UNIT
Static						•		
Drain-source breakdown voltage	V _{DS}	V _{GS} =	= 0 V, I _D = 3	250 µA	600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C,	I _D = 10 mA	-	0.58	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D =	250 µA	2.0	-	4.0	V
			$V_{GS} = \pm 20$	V	-	-	± 100	nA
Gate-source leakage	I _{GSS}		V _{GS} = ± 30	V	-	-	± 1	μA
7		V _{DS} =	= 600 V, V _G	_{iS} = 0 V	-	-	1	•
Zero gate voltage drain current	I _{DSS}	V _{DS} = 480 V	′, V _{GS} = 0 \	/, T _J = 125 °C	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	T	_D = 14 A	-	0.085	0.098	Ω
Forward transconductance	9 _{fs}	V _{DS}	= 30 V, I _D :	= 14 A	-	7.6	-	S
Dynamic						•		
Input capacitance	C _{iss}		V _{GS} = 0 V, V _{DS} = 100 V,		-	2614	-	
Output capacitance	C _{oss}				-	125	-	
Reverse transfer capacitance	C _{rss}	f = 1 MHz		-	5	-	pF	
Effective output capacitance, energy related ^a	C _{o(er)}	V_{DS} = 0 V to 480 V, V_{GS} = 0 V		-	86	-		
Effective output capacitance, time related ^b	C _{o(tr)}			-	444	-		
Total gate charge	Qg				-	86	129	
Gate-source charge	Q _{gs}	V _{GS} = 10 V I _D = 10 A, V _{DS} = 480 V		-	20	-	nC	
Gate-drain charge	Q _{gd}				-	44	-	1
Turn-on delay time	t _{d(on)}		•		-	29	58	
Rise time	t _r	- V _{DD} =	$\label{eq:VDD} \begin{array}{l} V_{\text{DD}} = 480 \; \text{V}, \; I_{\text{D}} = 14 \; \text{A}, \\ V_{\text{GS}} = 10 \; \text{V}, \; R_{\text{g}} = 9.1 \; \Omega \end{array}$		-	75	113	ns
Turn-off delay time	t _{d(off)}				-	84	126	
Fall time	t _f				-	54	81	
Gate input resistance	Rg	f = 1 MHz		0.2	0.5	1.0	Ω	
Drain-Source Body Diode Characteristic						•		
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	29	Δ	
Pulsed diode forward current	I _{SM}			-	-	76	A	
Diode forward voltage	V _{SD}	T _J = 25 °C	C, I _S = 14 A	A, V _{GS} = 0 V	-	0.9	1.2	V
Reverse recovery time	t _{rr}				-	386	772	ns
Reverse recovery charge	Q _{rr}	T _J = 25 °C, I _F = I _S = 14 A, dl/dt = 100 A/μs, V _B = 25 V		-	6	12	μC	
Reverse recovery current	I _{RRM}		, σο , v μο,	•K = 20 V	-	25	-	A

Notes

a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DS}

b. Coss(tr) is a fixed capacitance that gives the same charging time as Coss while VDS is rising from 0 % to 80 % VDS



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

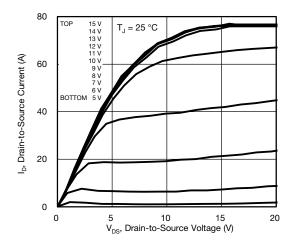


Fig. 1 - Typical Output Characteristics

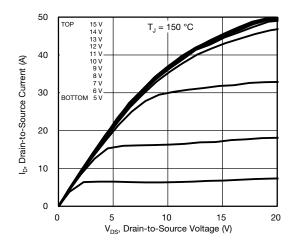


Fig. 2 - Typical Output Characteristics

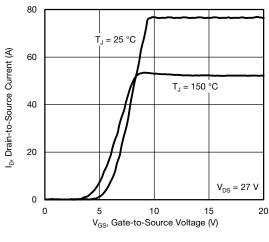


Fig. 3 - Typical Transfer Characteristics

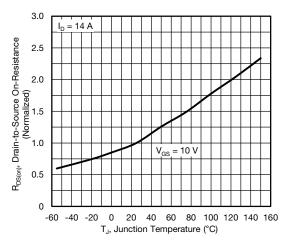


Fig. 4 - Normalized On-Resistance vs. Temperature

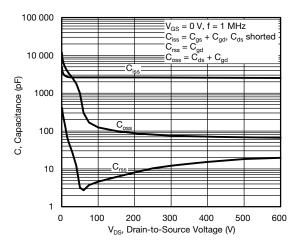


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

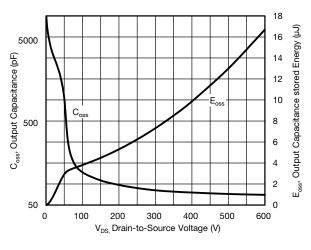


Fig. 6 - C_{OSS} and E_{OSS} vs. V_{DS}

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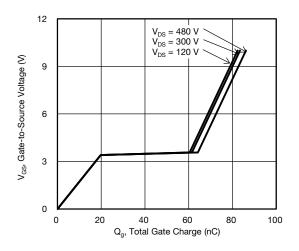


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

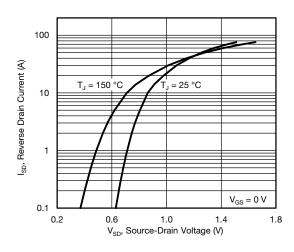


Fig. 8 - Typical Source-Drain Diode Forward Voltage

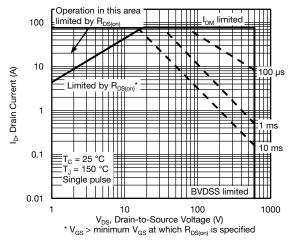


Fig. 9 - Maximum Safe Operating Area

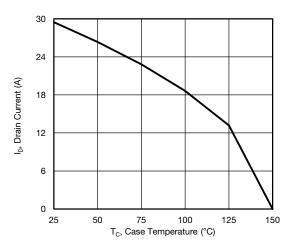


Fig. 10 - Maximum Drain Current vs. Case Temperature

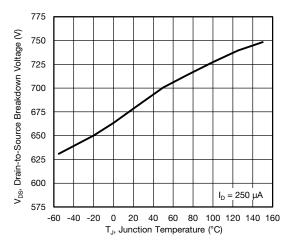
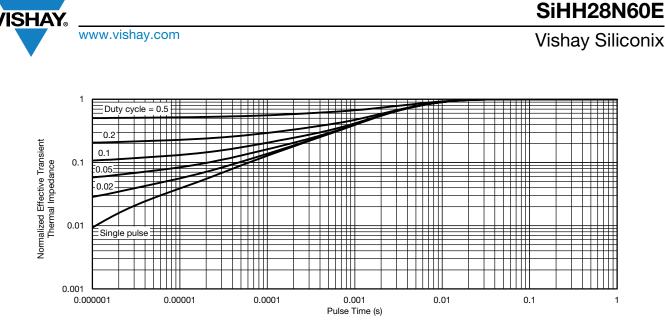


Fig. 11 - Temperature vs. Drain-to-Source Voltage

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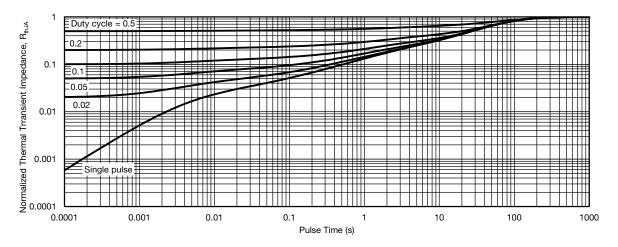


Fig. 13 - Normalized Thermal Transient Impedance, Junction-to-Ambient

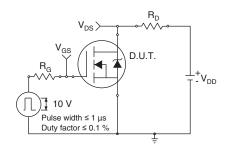


Fig. 14 - Switching Time Test Circuit

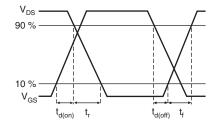


Fig. 15 - Switching Time Waveforms

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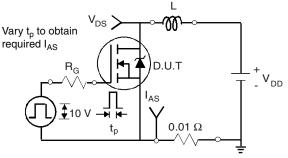


Fig. 16 - Unclamped Inductive Test Circuit

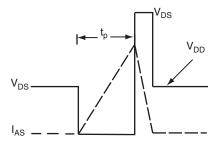


Fig. 17 - Unclamped Inductive Waveforms

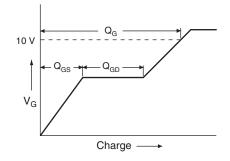


Fig. 18 - Basic Gate Charge Waveform

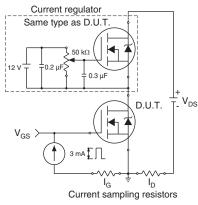


Fig. 19 - Gate Charge Test Circuit

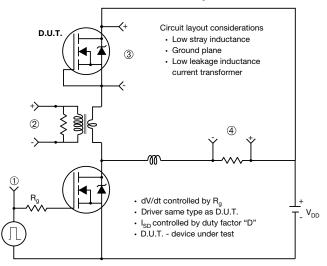
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S23-0652-Rev. D, 21-Aug-2023

Peak Diode Recovery dV/dt Test Circuit



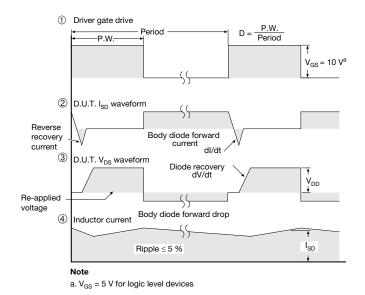


Fig. 20 - For N-Channel

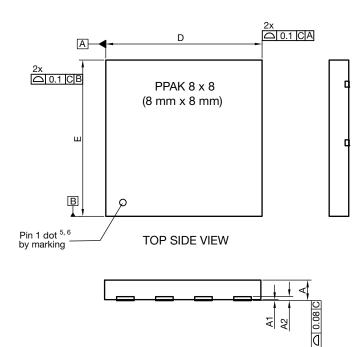
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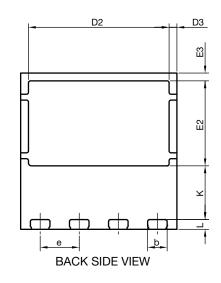
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PowerPAK[®] 8 x 8 Case Outline





DIM		MILLIMETERS			INCHES		
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
А	0.95	1.00	1.05	0.037	0.039	0.041	
A1	0.00	-	0.05	0.000	-	0.002	
A2		020 ref.		0.008 ref.			
b	0.95	1.00	1.05	0.037	0.039	0.041	
D	7.90	8.00	8.10	0.311	0.315	0.319	
D2	7.10	7.20	7.30	0.280	0.283	0.287	
D3		0.40 BSC		0.016 BSC			
е		2.00 BSC		0.079 BSC			
E	7.90	8.00	8.10	0.311	0.315	0.319	
E2	4.30	4.35	4.40	0.169	0.171	0.173	
E3		0.40 BSC			0.016 BSC		
К	2.75 BSC		0.108 BSC				
L	0.45	0.50	0.55	0.018	0.020	0.022	
N ⁽³⁾	8			8			

Notes

⁽¹⁾ Use millimeters as the primary measurement

⁽²⁾ Dimensioning and tolerances conform to ASME Y14.5 M - 1994

⁽³⁾ N is the number of terminals

⁽⁴⁾ The pin 1 identifier must be existed on the top surface of the package by using indentation mark or other feature of package body

⁽⁵⁾ Exact shape and size of this feature is optional

ECN: E20-0518-Rev. B, 28-Sep-2020 DWG: 6041

Revision: 28-Sep-2020

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Recommended Minimum PADs for PowerPAK[®] 8 mm x 8 mm



Dimensions in millimeters

Document Number: 68441



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